# UNITED STATES PATENT AND TRADEMARK OFFICE CERTIFICATE OF CORRECTION

PATENT NO. : 7,037,862 B2 Page 1 of 2

APPLICATION NO. : 09/881408 DATED : May 2, 2006

INVENTOR(S) : Kie Y. Ahn and Leonard Forbes

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

### Title page item 56

Pg. 2, col. 1, U.S. PATENT DOCUMENTS -

Please insert the following patents:

6,013,553	*	1/2000	Wallace et al.
6,348,373	*	2/2002	Ma et al.
6,407,435		6/2002	Ma et al.
6,495,474		12/2002	Rafferty et al.
6,573,160		6/2003	Taylor et al.
6,632,729	*	10/2003	Paton
6,679,996	*	1/2004	Yao
6,713,846		3/2004	Senzaki
6,784,508	*	8/2004	Tsunashima et al.
2002/0190302		12/2002	Bojarczuk et al

### Col. 2, line 24 -

Replace "additional requirements. Thus it would desirable provide" With --additional requirements. Thus it would be desirable to provide-

#### Col. 5, line 37 –

Replace "evaporative processes and in particular an electron beam" With --evaporative process and in particular an electron beam--

### Col. 6, line 7 –

Replace "by using a physical deposition (PVD) method as previously" With --by using a physical vapor deposition (PVD) method as previously--

#### Col. 7, line 67 –

Replace "oxidation conditions only one effective method and that" With --oxidation conditions represent only one effective method and that--

#### Col. 9, line 13 -

Replace "will be understood that the selection of Hf and La form the" With --will be understood that the selection of Hf and La to form the-

#### Col. 9, line 36, claim 1 –

Replace "the second layer to temperature effective to form a first" With --the second layer to a temperature effective to form a first--

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Col. 9, line 61, claim 8 –

Replace "heating to a temperature from about 200° C. to about 400 C." With --heating to a temperature from about 200° C. to about 400° C.--

Col. 10, line 42, claim 17 -

Replace "heating the metal lever and layer of silicon dioxide to a" With --heating the metal layer and layer of silicon dioxide to a--

Col. 10, line 47, claim 17 -

Replace "dielectric lever over the surface, all the metal of the first" With --dielectric layer over the surface, all the metal of the first--

Col. 11, line 17, claim 22 –

Replace "heating to a temperature from about 200° C. to about 200°." With --heating to a temperature from about 200° C. to about 400°--

Col. 12, lines 15-16, claim 23 –

Replace "the raction chamber and heating the hafnium-containing" With --the reaction chamber and heating the hafnium-containing--

Signed and Sealed this

Twenty-fifth Day of November, 2008

JON W. DUDAS
Director of the United States Patent and Trademark Office